

## **STPS30170DJF**

### Power Schottky rectifier

### **Features**

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- Avalanche capability specified
- ECOPACK®2 compliant component

### **Description**

This Schottky rectifier is designed for switch mode power supply and high frequency DC to DC converters.

Packaged in PowerFLAT™, this device is intended for use in low voltage, high frequency inverters, free-wheeling and polarity protection applications.

Its low profile was especially designed to be used in applications with space-saving constraints.

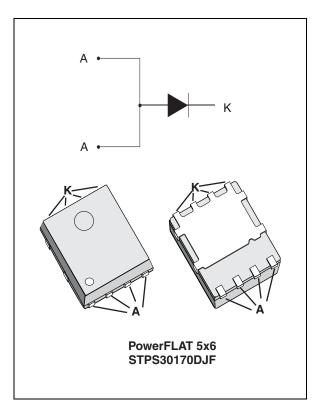


Table 1. Device summary

Symbol	Value
I <sub>F(AV)</sub>	30 A
$V_{RRM}$	170 V
T <sub>j</sub> (max)	150 °C
V <sub>F</sub> (typ)	0.65 V

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**STPS30170DJF Characteristics** 

#### **Characteristics** 1

Table 2. Absolute ratings (limiting values, anode terminals short circuited)

Symbol	Parameter	Value	Unit	
$V_{RRM}$	Repetitive peak reverse voltage	170	V	
I <sub>F(RMS)</sub>	Forward rms current	Forward rms current		
I <sub>F(AV)</sub>	Average forward current $T_c = 80$ °C, $\delta = 0.5$		30	Α
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ ms sinusoidal} $ $T_c = 25  ^{\circ}\text{C}$		200	Α
P <sub>ARM</sub>	Repetitive peak avalanche power	12500	W	
T <sub>stg</sub>	Storage temperature range	-65 to + 175	°C	
T <sub>j</sub>	Maximum operating junction temperatu	150	°C	

 $<sup>\</sup>frac{dPtot}{dTj} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value	Unit
R <sub>th(j-c)</sub>	Junction to case	2.5	°C/W

Table 4. Static electrical characteristics (anode terminals short circuited)

Symbol	Parameter	Test conditions		Min.	Тур.	Max.	Unit
I <sub>B</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	$V_R = V_{RRM}$	-	-	15	μΑ
'R`	neverse leakage current	T <sub>j</sub> = 125 °C		-	4	12	mA
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A	-	-	0.88	
V <sub>E</sub> <sup>(2)</sup>	V <sub>F</sub> <sup>(2)</sup> Forward voltage drop	T <sub>j</sub> = 125 °C		-	0.65	0.70	V
VETTOIWAI	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 30 A	-	-	0.95	<b>V</b>
		T <sub>j</sub> = 125 °C		-	0.71	0.79	

<sup>1.</sup> Pulse test:  $t_p = 5 \text{ ms}$ ,  $\delta < 2\%$ 

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To evaluate the conduction losses use the following equation: P = 0.65 x  $I_{F(AV)}$  + 0.0046  $I_{F}^{2}_{(RMS)}$ 

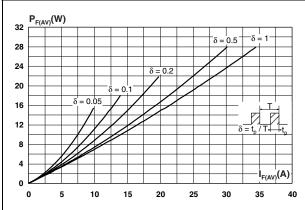
$$P = 0.65 \times I_{F(AV)} + 0.0046 I_{F}^{2}(BMS)$$

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<sup>2.</sup> Pulse test:  $t_p$  = 380  $\mu$ s,  $\delta$  < 2%

STPS30170DJF Characteristics

Figure 1. Average forward power dissipation Figure 2. Average forward current versus awbient temperature ( $\delta$  = 0.5)



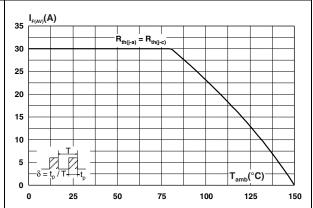
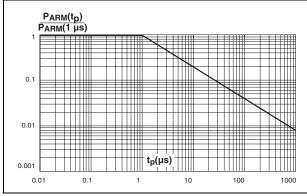


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature



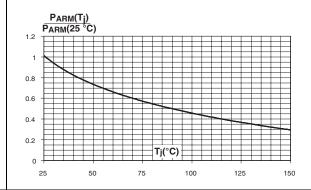
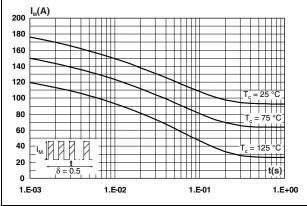
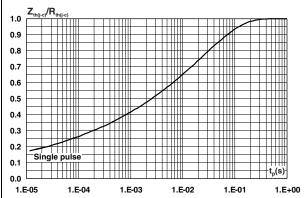


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values)

Figure 6. Relative variation of thermal impedance, junction to case, versus pulse duration

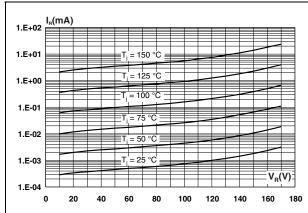




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Figure 7. Reverse leakage current versus reverse voltage applied (typical values)

Figure 8. Junction capacitance versus reverse voltage applied (typical values)



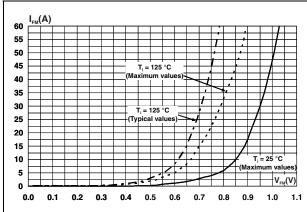
1000 C(pF)

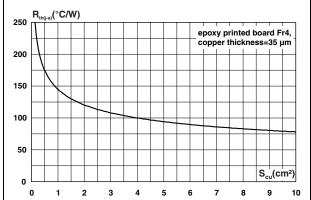
F = 1 MHz
V<sub>osc</sub> = 30 mV<sub>RMS</sub>
T = 25 °C

V<sub>R</sub>(V)
10
1 10 100 1000

Figure 9. Forward voltage drop versus forward current

Figure 10. Thermal resistance, junction to ambient, versus copper surface under tab





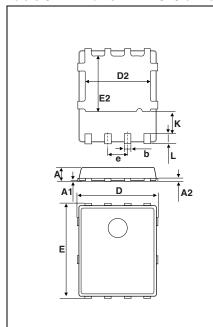
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## 2 Package information

- Epoxy meets UL94,V0
- Lead-free package

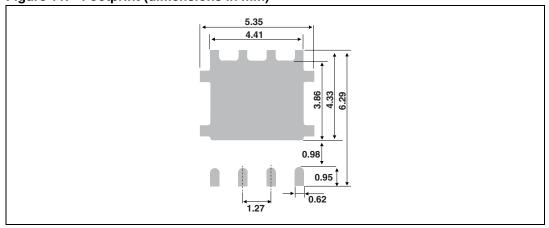
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Table 5. PowerFLAT 5x6 dimensions



	Dimensions					
Ref.	M	Millimeters				
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	0.80		1.00	0.031		0.039
A1	0.02		0.05	0.001		0.002
A2		0.25			0.010	
b	0.30		0.50	0.012		0.020
D		5.20			0.205	
D2	4.11		4.31	0.162		0.170
е		1.27			0.050	
Е		6.15			0.242	
E2	3.50		3.70	0.138		0.146
L	0.50		0.80	0.020		0.031
K	1.275		1.575	0.050		0.062

Figure 11. Footprint (dimensions in mm)



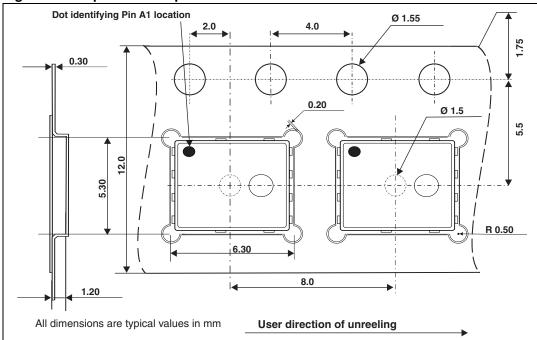


Figure 12. Tape and reel specifications

# 3 Ordering information

Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS30170DJF-TR	PS30 170	PowerFLAT 5x6	95 mg	3000	Tape and reel

# 4 Revision history

Table 7. Document revision history

Date	Revision	Changes
06-Nov-2009	1	First issue.
30-Jul-2010	2	Replace Power QFN with PowerFLAT.
20-May-2011	3	Updated package graphics. Updated base quantity and marking in <i>Table 6</i> . Added <i>Figure 12</i> .

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